

# General Purpose Transistor Array One Differentially Connected Pair and Three Isolated Transistor Arrays

The MC3346 is designed for general purpose, low power applications for consumer and industrial designs.

- Guaranteed Base-Emitter Voltage Matching
- Operating Current Range Specified: 10 μA to 10 mA
- Five General Purpose Transistors in One Package

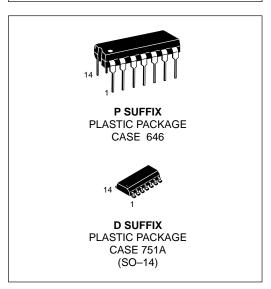
### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCEO	15	Vdc
Collector-Base Voltage	Vсво	20	Vdc
Emitter–Base Voltage	V <sub>EB</sub>	5.0	Vdc
Collector-Substrate Voltage	VCIO	20	Vdc
Collector Current – Continuous	IC	50	mAdc
Total Power Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	PD	1.2 10	W mW/°C
Operating Temperature Range	TA	-40 to +85	°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C

# MC3346

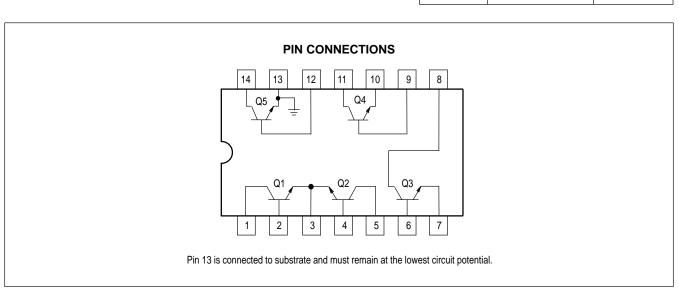
# GENERAL PURPOSE TRANSISTOR ARRAY

SEMICONDUCTOR TECHNICAL DATA



## ORDERING INFORMATION

0.12_10 0.1				
Devic	е	Operating Temperature Range	Package	
MC334	6D	$T_{\Delta} = -40^{\circ} \text{ to } +85^{\circ}\text{C}$	SO-14	
MC335	6P	1A = -40 to +65 C	Plastic DIP	



# MC3346

# ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = +25°C, unless otherwise noted.)

Characteristics	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTICS					
Collector–Base Breakdown Voltage ( $I_C = 10 \mu Adc$ )	V(BR)CBO	20	60	_	Vdc
Collector–Emitter Breakdown Voltage (I <sub>C</sub> = 1.0 mAdc)	V(BR)CEO	15	-	-	Vdc
Collector–Substrate Breakdown Voltage (I <sub>C</sub> = 10 μA)	V(BR)CIO	20	60	-	Vdc
Emitter–Base Breakdown Voltage (I <sub>E</sub> = 10 μAdc)	V(BR)EBO	5.0	7.0	-	Vdc
Collector–Base Cutoff Current (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0)	ICBO	-	-	40	nAdc
DC Current Gain (IC = 10 mAdc, VCE = $3.0 \text{ Vdc}$ ) (IC = $1.0 \text{ mAdc}$ , VCE = $3.0 \text{ Vdc}$ ) (IC = $10  \mu\text{Adc}$ , VCE = $3.0 \text{ Vdc}$ )	hFE	- 40 -	140 130 60	- - -	-
Base–Emitter Voltage ( $V_{CE} = 3.0 \text{ Vdc}$ , $I_{E} = 1.0 \text{ mAdc}$ ) ( $V_{CE} = 3.0 \text{ Vdc}$ , $I_{E} = 10 \text{ mAdc}$ )	Vве	_ _	0.72 0.8	- -	Vdc
Input Offset Current for Matched Pair Q1 and Q2 (V <sub>CE</sub> = 3.0 Vdc, I <sub>C</sub> = 1.0 mAdc)	1 01 - 1 02	-	0.3	2.0	μAdc
Magnitude of Input Offset Voltage (V <sub>CE</sub> = 3.0 Vdc, I <sub>C</sub> = 1.0 mAdc)	-	-	0.5	5.0	mVdc
Temperature Coefficient of Base–Emitter Voltage (V <sub>CE</sub> = 3.0 Vdc, I <sub>C</sub> = 1.0 mAdc)	$\frac{\Delta V_{BE}}{D_{T}}$	-	-1.9	-	mV/°C
Temperature Coefficient	<u> ΔV<sub>IO</sub> </u> D <sub>T</sub>	-	1.0	-	μV/°C
Collector–Emitter Cutoff Current (V <sub>CE</sub> = 10 Vdc, I <sub>B</sub> = 0)	ICEO	-	_	0.5	μAdc
DYNAMIC CHARACTERISTICS	<u>.</u>	•			
Low Frequency Noise Figure (V <sub>CE</sub> = 3.0 Vdc, I <sub>C</sub> = 100 μAdc, R <sub>S</sub> = 1.0 kΩ, f = 1.0 kHz)	NF	_	3.25	-	dB
Forward Current Transfer Ratio $(V_{CE} = 3.0 \text{ Vdc}, I_{C} = 1.0 \text{ mAdc}, f = 1.0 \text{ kHz})$	hFE	-	110	-	-
Short Circuit Input Impedance (V <sub>CE</sub> = 3.0 Vdc, I <sub>C</sub> = 1.0 mAdc)	h <sub>ie</sub>	_	3.5	-	kΩ
Open Circuit Output Impedance (V <sub>CE</sub> = 3.0 Vdc, I <sub>C</sub> = 1.0 mAdc)	h <sub>oe</sub>	_	15.6	-	μmhos
Reverse Voltage Transfer Ratio (V <sub>CE</sub> = 3.0 Vdc, I <sub>C</sub> = 1.0 mAdc)	h <sub>re</sub>	_	1.8	-	x10 <sup>-4</sup>
Forward Transfer Admittance (V <sub>CE</sub> = 3.0 Vdc, I <sub>C</sub> = 1.0 mAdc, f = 1.0 MHz)	Уfе	-	31–j1.5	-	_
Input Admittance (V <sub>CE</sub> = 3.0 Vdc, I <sub>C</sub> = 1.0 mAdc, f = 1.0 MHz)	Уіе	_	0.3 + j0.04	-	_
Output Admittance ( $V_{CE} = 3.0 \text{ Vdc}$ , $I_{C} = 1.0 \text{ mAdc}$ , $f = 1.0 \text{ MHz}$ )	Уое	-	0.001 + j0.03	-	-
Current–Gain – Bandwidth Product (V <sub>CE</sub> = 3.0 Vdc, I <sub>C</sub> = 3.0 mAdc)	fT	300	550	_	MHz
Emitter–Base Capacitance (V <sub>EB</sub> = 3.0 Vdc, I <sub>E</sub> = 0)	C <sub>eb</sub>	-	0.6	-	pF
Collector–Base Capacitance $(V_{CB} = 3.0 \text{ Vdc}, I_{C} = 0)$	C <sub>cb</sub>	-	0.58	_	pF
Collector–Substrate Capacitance (V <sub>CS</sub> = 3.0 Vdc, I <sub>C</sub> = 0)	C <sub>Cl</sub>	-	2.8	_	pF

Figure 1. Collector Cutoff Current versus Temperature (Each Transistor)

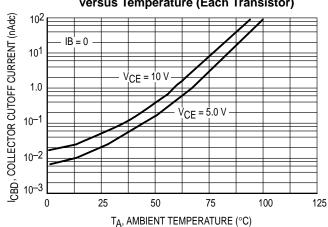


Figure 2. Collector Cutoff Current versus Temperature (Each Transistor)

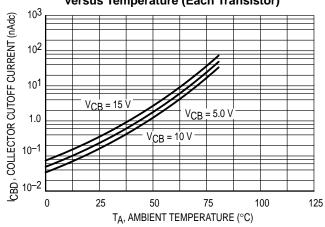


Figure 3. Input Offset Characteristics for Q1 and Q2

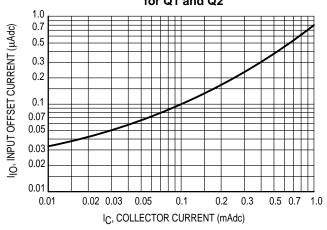


Figure 4. Base–Emitter and Input Offset Voltage Characteristics

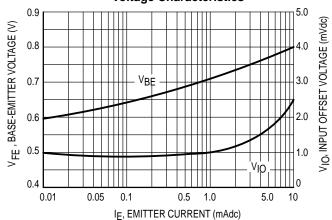
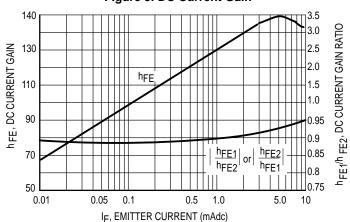
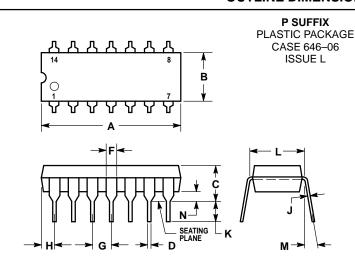


Figure 5. DC Current Gain



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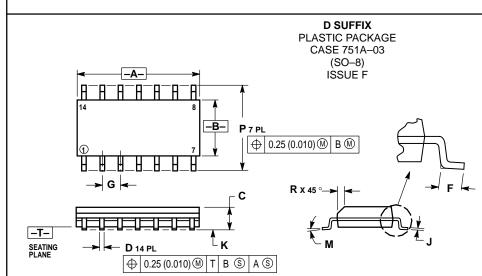
### **OUTLINE DIMENSIONS**



#### NOTES

- LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
- 4. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.715	0.770	18.16	19.56	
В	0.240	0.260	6.10	6.60	
С	0.145	0.185	3.69	4.69	
D	0.015	0.021	0.38	0.53	
F	0.040	0.070	1.02	1.78	
Ð	0.100 BSC		2.54 BSC		
H	0.052	0.095	1.32	2.41	
J	0.008	0.015	0.20	0.38	
K	0.115	0.135	2.92	3.43	
L	0.300 BSC		7.62 BSC		
М	0°	10°	0°	10°	
Ν	0.015	0.039	0.39	1.01	



#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
   MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	8.55	8.75	0.337	0.344	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27 BSC		0.050 BSC		
٦	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0 °	7°	0 °	7°	
Р	5.80	6.20	0.228	0.244	
R	0.25	0.50	0.010	0.019	

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